

AF/6A 1765
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Correspondence and Mail
BOX AF



Response Under 37 C.F.R. 1.116
Expediting Procedure
Examining Group 1765

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: HENNHÖFER ET AL.

SERIAL NO.: 09/032,305

EXAMINER: R. KUNEMUND

FILED: FEBRUARY 27, 1998

GROUP: 1765

TITLE: PROCESS FOR TREATING A POLISHED SEMICONDUCTOR WAFER
IMMEDIATELY AFTER THE SEMICONDUCTOR WAFER HAS BEEN
POLISHED

TO 1100 MAIL ROOM

SEP 15 2000

RECEIVED

done & enter
over
9/2/00

Entered - CPA
10/6/00

AMENDMENT IN RESPONSE TO FINAL OFFICE ACTION

ATT: BOX AF
Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Final Office Action dated JUNE 12, 2000
please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please cancel claim 1 without prejudice and please replace by
inserting new claims 14 as follows:

- Sub
D1
C
14. Process for treating a semiconductor wafer, comprising
polishing the semiconductor wafer;
immediately after polishing the semiconductor wafer
removing the semiconductor wafer from a polishing plate;
bringing the semiconductor wafer into contact with an